



APPROVAL SHEET

MODEL NO.: SMD1210 Series

CUSTOMER:

CUSTOMER'S APPROVAL:

AUTHORIZED SIGNATURE/STAMP:

DATE

MANUFACTURER:

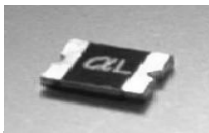
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Submitted by:

Approved by:

DATE:



SMD1210 Series

Features

- Surface Mount Devices
- Lead free device
- Size 3.2*2.5mm/0.12*0.10 inch
- Surface Mount packaging for automated assembly

Applications

- Almost anywhere there is a low voltage power supply, up to 30V and a load to be protected, including:
- Computer mother board, Modem.
 - Telecommunication equipments.

Alpha-Top (Sea&Land Alliance)

Performance Specification

Model	Marking	V_{max}	I_{max}	I_{hold}	I_{trip}	P_d	Maximum Time To Trip		Resistance	
		(Vdc)	(A)	@25°C (A)	@25°C (A)	Typ. (W)	Current (A)	Time (Sec)	$R_{i_{min}}$ (Ω)	$R_{1_{max}}$ (Ω)
SMD1210-005	α A	30	100	0.05	0.15	0.6	0.25	1.50	2.800	50.000
SMD1210-010	α B	30	100	0.10	0.30	0.6	0.50	0.60	0.800	15.000
SMD1210-020	α C	30	100	0.20	0.40	0.6	8.0	0.02	0.400	5.000
SMD1210-035	α D	6	100	0.35	0.75	0.6	8.0	0.20	0.200	1.300
SMD1210-050	α F	13.2	100	0.50	1.00	0.6	8.0	0.10	0.180	0.900
SMD1210-075	α G	6	100	0.75	1.50	0.6	8.0	0.10	0.070	0.400
SMD1210-110	α H	6	100	1.10	2.20	0.6	8.0	0.30	0.050	0.210
SMD1210-150	α L	6	100	1.50	3.00	0.6	8.0	0.50	0.030	0.110
SMD1210-175	α N	6	100	1.75	3.50	0.8	8.0	0.60	0.020	0.080
SMD1210-200	α S	6	100	2.00	4.00	0.8	8.0	1.00	0.015	0.070

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R_{i min/max} = Minimum/Maximum device resistance prior to tripping at 25°C.

R_{1 max} = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

AGENCY APPROVALS :

UL pending

Regulation/Standard:



2002/95/EC



EN14582

I_{hold} Versus Temperature

Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD1210-005	0.08	0.07	0.06	0.05	0.04	0.04	0.03	0.03	0.02
SMD1210-010	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.03
SMD1210-020	0.29	0.26	0.22	0.20	0.16	0.14	0.13	0.11	0.08
SMD1210-035	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
SMD1210-050	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28
SMD1210-075	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
SMD1210-110	1.69	1.48	1.29	1.10	0.88	0.76	0.65	0.57	0.43
SMD1210-150	2.13	1.92	1.71	1.50	1.26	1.14	1.01	0.89	0.71
SMD1210-175	2.54	2.30	2.02	1.75	1.47	1.33	1.18	1.05	0.86
SMD1210-200	2.90	2.63	2.31	2.00	1.68	1.52	1.35	1.20	0.98

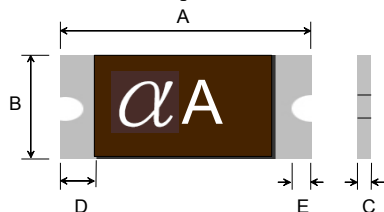
SMD1210 Series

Alpha-Top (Sea&Land Alliance)

Construction And Dimension (Unit:mm)

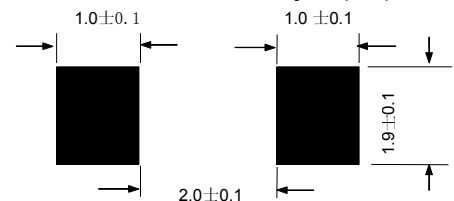
Model	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD1210-005	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-010	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-020	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-035	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-050	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-075	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-110	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.80	0.10	0.10
SMD1210-150	3.00	3.43	2.35	2.80	0.40	0.80	0.30	0.80	0.10	0.10
SMD1210-175	3.00	3.43	2.35	2.80	0.50	1.20	0.30	0.80	0.10	0.10
SMD1210-200	3.00	3.43	2.35	2.80	0.50	1.20	0.30	0.80	0.10	0.10

Dimensions & Marking



α = Trademark
A = Part identification

Recommended Pad Layout (mm)



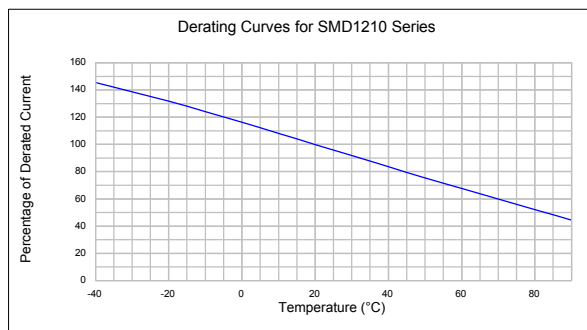
Termination Pad Characteristics

Terminal pad materials : Tin-plated Nickel-Copper
Terminal pad solderability : Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

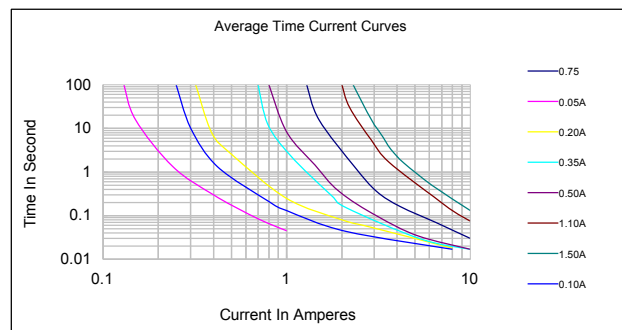
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



Typical Time-To-Trip At 25°C



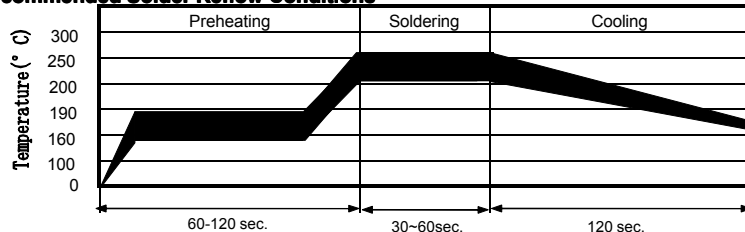
WARNING:

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

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Recommended Solder Reflow Conditions

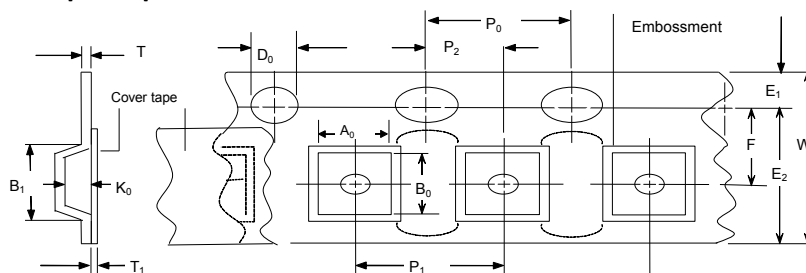


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
 - Devices are not designed to be wave soldered to the bottom side of the board.
 - Recommended maximum paste thickness is 0.25 mm (0.010 inch).
 - Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

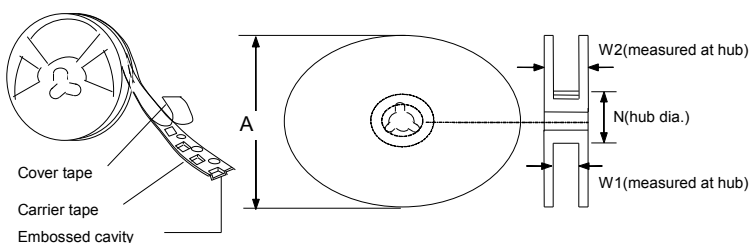
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-2
W	8.0 ± 0.20
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.10
A0	2.82 ± 0.10
B0	3.52 ± 0.10
B1max.	4.35
D0	1.5 + 0.1, -0.0
F	7.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
Tmax.	0.6
T1max.	0.1
K0	0.90 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	50
W1	8.4 + 1.5, -0.0
W2max.	22.4

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

Order Information

SMD1210	050	Packaging	Tape & Reel Quantity
Product name	Hold		050,075 4,000 pcs/reel
Size 3225 mm / 1210 inch	Current		The others 4,500 pcs/reel
SMD : surface mount device	0.50A		

Tape & reel packaging per EIA481-1

Labeling Information

